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Search statement 1

Query/Command: US6132851/PN

** SS 1: Results 1

Search statement 2

Query/Command: PRT FULL NONSTOP LEGALALL

1/1 PLUSPAT - ©QUESTEL-ORBIT

PN US6132851 A 20001017 [US6132851]

TI (A) Adhesive compositions and copper foils and copper clad laminates using same

PA (A) GA TEK INC (US)

GA-TEK Inc., Eastlake OH [US] PA₀

IN: (A) POUTASSE CHARLES A (US)

US26787794 19940628 [1994US-0267877] AP US26787794 19940628 [1994US-0267877] PR

IC (A) B32B-003/00

EC C08G-059/02

C08G-059/06

C08G-059/40

C09J-163/00 &B4B2

H05K-003/38D

T05K-003/02C ICO

T05K-003/38C

ORIGINAL (O): 428209000; CROSS-REFERENCE (X): 428408000 PCL 428413000 428417000 428418000 428446000 428457000 428901000 525109000 525113000

DT Corresponding document

CT US3496130; US3935053; US4020225; US4246162; US4343843; US5061550; US5071914; EP0012714; EP0148493; EP0371242; JP62-101674 Search Report for European Appl. 95304380.9.

> Epoxy Resins, Chem. & Tech., May, 8, 1989 Marcel Dekker Inc., pp. 683-691, 1089-1095.

STG (A) United States patent

AB This invention relates to an adhesive composition, comprising: (A) at least one phenolic resole resin; and (B) the product made by reacting (B-1) at least one difunctional epoxy resin, with (B-2) at least one compound represented by the formula (Chemical Structure image '1' not included in text) wherein in Formulae (I) and (II): G, T and Q are each independently functional groups selected from the group consisting of COOH, OH, SH, NH2, NHR1, (NHC(.dbd.NH))m NH2, R2 COOH, NR12, C(O)NHR1, R2 NR12, R2 OH, R2 SH, R2 NH2 and R2 NHR1, wherein R1 is a hydrocarbon group, R2 is an alkylene or alkylidene group and m is a number in the range of 1 to about 4; T can also be R1, OR1 or SO2 C6 H4 -- NH2; and Q can also be H. The invention also relates to copper foils having the foregoing adhesive composition adhered to at least one side thereof to enhance the adhesion between said foils and dielectric substrates. The invention also relates to laminates comprising copper foil, a dielectric substrate, and an adhesion-promoting layer comprising the foregoing adhesive composition disposed between and adhered to the foil and the substrate.

UP 2000-44 1/1 LGST - ©EPO

PN - US6132851 A 20001017 [US6132851]

AP - US26787794 19940628 [1994US-0267877]

ACT - 20000522 US/AS-A

ASSIGNMENT

OWNER: GA-TEK INC. 34929 CURTIS BOULEVARD EASTLAKE OHIO 4;

EFFECTIVE DATE: 19971030

CHANGE OF NAME; ASSIGNOR: GOULD ELECTRONICS,

INC.;REEL/FRAME:010923/0373

20031111 US/RF-A

REISSUE APPLICATION FILED EFFECTIVE DATE: 20021017

20031118 US/RF-A

REISSUE APPLICATION FILED EFFECTIVE DATE: 20021017

UP - 2004-29

1 / 1 CRXX - ©CLAIMS/RRX

PN - 6,132,851 A 20001017 [US6132851]

PA - GA-TEK Inc

ACT - 20031001 REASSIGNED

BILL OF SALE AND INSTRUMENT OF ASSIGNMENT AND

ASSUMPTION

Assignor: GOULD ELECTRONICS INC. DATE SIGNED: 09/30/2003

Assignee: NIKKO MATERIALS USA, INC. 125 NORTH PRICE ROAD

CHANDLER ARIZONA 85224

Reel 014022/Frame 0437

Contact: JONES DAY DEBRA L. PEJEAU 901 LAKESIDE AVENUE NORTH

POINT CLEVELAND, OH 44114

20031017 REISSUE REQUESTED ISSUE DATE OF O.G.: 20031111

REISSUE REQUEST NUMBER: 10/617653

EXAMINATION GROUP RESPONSIBLE FOR REISSUEPROCESS: 1774

Reissue Patent Number:

20031017 REISSUE REQUESTED
ISSUE DATE OF O.G.: 20031118
REISSUE REQUEST NUMBER: 10/659793
EXAMINATION GROUP RESPONSIBLE FOR REISSUEPROCESS: 1774

Reissue Patent Number:

Search statement 2

Query/Command: FILE INPADOC

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Legal-Status informations
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Estimated total session cost
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Legal-Status informations
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                                               10.26 USD
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For information on content, (..) INFO INPD.

Search statement 1

Query/Command: FAM US6132851/PN

1 Patent Groups

** SS 1: Results 5

Search statement 2

Query/Command: FAMSTATE NONSTOP

1/5 INPADOC - ©INPADOC

PN - CN 1118367 A 19960313 [CN1118367]

TI - ADHESIVE COMPOSITIONS AND COPPER FOILS AND COPPER CLAD LAMINATES USING SAME

IN - POUTASSE CHARLES A [US]

PA - GOULD ELECTRONICS INC [US]

AP - CN 95107661/95-A 19950623 [1995CN-0107661]

PR - US 267877/94-A 19940628 [1994US-0267877]

IC - C09J-161/06; B32B-015/20

2/5 INPADOC - ©INPADOC

PN - EP 691389 A1 19960110 [EP-691389]

TI - ADHESIVE COMPOSITIONS AND COPPER FOIL AND COPPER CLAD LAMINATES USING SAME

LA - ENG

IN - POUTASSE CHARLES A [US]

PA - GOULD ELECTRONICS INC [US]

AP - EP 95304380/95-A 19950622 [1995EP-0304380]

PR - US 267877/94-A 19940628 [1994US-0267877]

IC - C09J-163/00; C08L-063/00; H05K-003/38

DS - AT* DE* FR* GB* IT* LU*

1/1 LEGALI - ©EPO

PN - EP0691389 A1 19960110 [EP-691389]

AP - EP95304380 19950622 [1995EP-0304380]

ACTE - 19960110 EP/AK-A [+]

DESIGNATED CONTRACTING STATES:

AT DE FR GB IT LU

19960807 EP/17P-A [+] REQUEST FOR EXAMINATION FILED EFFECTIVE DATE: 19960611

20000517 EP/RAP1-A APPLICANT REASSIGNMENT (CORRECTION) OWNER: GA-TEK, INC. (DOING BUSINESS AS GOULD ELECTRONICS

20001011 EP/17Q-A [+] FIRST EXAMINATION REPORT **EFFECTIVE DATE: 20000824**

20020612 EP/18D-A [-] DEEMED TO BE WITHDRAWN EFFECTIVE DATE: 20011128

UP 2003-22

3/5 INPADOC - @INPADOC

JP 8048960 A2 19960220 [JP08048960] PN

ADHESIVE COMPOSITION, COPPER FOIL AND COPPER-CLAD TI LAMINATE CONSISTING OF THEM

- CHIYAARUZU EI POOTATSUSE IN

- GOULD ELECTRONICS INC PA

AP - JP 162675/95-A 19950628 [1995JP-0162675]

PR - US 267877/94-A 19940628 [1994US-0267877]

C09J-163/00; C08G-059/14; H05K-003/38; B32B-015/08 IC

4/5 INPADOC - ©INPADOC

PN TW 383333 B 20000301 [TW-383333]

ADHESIVE COMPOSITIONS AND COPPER FOILS AND COPPER CLAD TI LAMINATES USING SAME

- POUTASSE CHARLES A [US] IN

- GOULD ELECTRONICS INC [US] PA

AP - TW 84103987/95-A 19950422 [1995TW-0103987]

- US 267877/94-A 19940628 [1994US-0267877] PR

C09J-161/00; C09J-163/00 IC

1/1 LEGALI - ©EPO

TW383333 B 20000301 [TW-383333] PN

TW84103987 19950422 [1995TW-0103987] AP

ACTE -20000704 TW/GD4A-A [+] ISSUE OF PATENT CERTIFICATE FOR GRANTED INVENTION PATENT 20040221 TW/MM4A-A [-] ANNULMENT OR LAPSE OF PATENT DUE TO NON-PAYMENT OF FEES

UP - 2004-31

5/5 INPADOC - ©INPADOC

PN - US 6132851 A 20001017 [US6132851]

TI - ADHESIVE COMPOSITIONS AND COPPER FOILS AND COPPER CLAD LAMINATES USING SAME

IN - POUTASSE CHARLES A [US]

PA - GA TEK INC [US]

AP - US 267877/94-A 19940628 [1994US-0267877] **PR** - US 267877/94-A 19940628 [1994US-0267877]

IC - B32B-003/00

1/1 LEGALI - ©EPO

PN - US6132851 A 20001017 [US6132851]

AP - US26787794 19940628 [1994US-0267877]

ACTE - 20000522 US/AS-A

ASSIGNMENT

OWNER: GA-TEK INC. 34929 CURTIS BOULEVARD EASTLAKE OHIO 4;

EFFECTIVE DATE: 19971030

CHANGE OF NAME; ASSIGNOR: GOULD ELECTRONICS,

INC.;REEL/FRAME:010923/0373

20031111 US/RF-A

REISSUE APPLICATION FILED

EFFECTIVE DATE: 20021017

20031118 US/RF-A

REISSUE APPLICATION FILED

EFFECTIVE DATE: 20021017

UP - 2004-29

Search statement 2

PATNO IS 6132851

DATE: SEPTEMBER 10, 2004 LIBRARY: PATENT FILE: ALL

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PATNO IS 6132851

Number of PATENTS found with your search request through: LEVEL $\ 1\dots \ 1$

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For further explanation, press the H key (for HELP) and then the ENTER key.

LEVEL 1 - 1 PATENT

1. 6132851 , October 17, 2000 , Adhesive compositions and copper foils and copper clad laminates using same, Poutasse, Charles A. - Cleveland, Ohio, United States (US), 267877 (08), GA-TEK Inc., Eastlake, Ohio, United States (US), 02, June 28, 1994 - ASSIGNMENT OF ASSIGNORS INTEREST (SEE DOCUMENT FOR DETAILS) ., GOULD ELECTRONICS INC. 35129 CURTIS BOULEVARD EASTLAKE, OH 44095-4001, Reel and Frame Number: 007071/0747 May 22, 2000 - CHANGE OF NAME (SEE DOCUMENT FOR DETAILS)., GA-TEK INC. 34929 CURTIS BOULEVARD EASTLAKE OHIO 44095, Reel and Frame Number: 010923/0373 October 1, 2003 - BILL OF SALE AND INSTRUMENT OF ASSIGNMENT AND ASSUMPTION, NIKKO MATERIALS USA, INC. 125 NORTH PRICE ROAD CHANDLER ARIZONA 85224, Reel and Frame Number: 014022/0437

CORE TERMS: foil, sup, sub, adhesive, composition, copper, layer, epoxy, resin, substrate ...

LEVEL 1 - 1 OF 1 PATENT

UNITED STATES PATENT AND TRADEMARK OFFICE GRANTED PATENT

6132851

October 17, 2000

Adhesive compositions and copper foils and copper clad laminates using same

REISSUE: October 17, 2002 - Reissue Application filed Ex. Gp.: 1774; Re. S.N. 10/617,653 (O.G. November 11, 2003)

October 17, 2002 - Reissue Application filed Ex. Gp.: 1774; Re. S.N. 10/659,793 (O.G. November 18, 2003)

APPL-NO: 267877 (08)

FILED-DATE: June 28, 1994

GRANTED-DATE: October 17, 2000

CORE TERMS: foil, sup, sub, adhesive, composition, copper, layer, epoxy, resin,

substrate ...

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